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Attorney's Docket No. 042390.P5832

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application for:

Donald S. Gardner, et al.

Serial No. 09/253,306

Filed: February 19, 1999

For: **INTERCONNECTION ALLOY FOR
INTEGRATED CIRCUITS**

Examiner: Tran, T.

Art Unit: 2811

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Box Non-Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

AMENDMENT AND RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action mailed March 27, 2002, in connection with the above referenced patent application, the Applicants respectfully request entry of the following amendments and request reconsideration in view of the following remarks.

IN THE CLAIMS:

Presented below is the amended claim in clean unmarked form. The claim, in marked-up form, is presented as an attachment.

- 21
- 1 20. (Amended) The multilayered structure of claim 16, wherein the aluminum-copper-
 - 2 titanium alloy layer comprises about 0.5 atomic percent copper and about 0.1 atomic percent
 - 3 titanium.